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(12) **United States Design Patent** (10) **Patent No.:** **US D783,351 S**  
**Fujino et al.** (45) **Date of Patent:** **\*\* Apr. 11, 2017**

(54) **GAS NOZZLE SUBSTRATE PROCESSING APPARATUS**

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(73) Assignee: **HITACHI KOKUSAI ELECTRIC INC.**, Tokyo (JP)

(\*\*) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** ..... **23-03**

(52) **U.S. Cl.**  
USPC ..... **D7/407**

(58) **Field of Classification Search**  
USPC ..... D7/407, 332, 334-337, 402-405, 391,  
D7/392.1; D23/127, 129, 415  
CPC ..... F23D 14/045; F23D 14/06; F23D 14/105;  
F23D 14/26; F23D 2203/102; F23D  
2900/14042; F23D 2900/14064; F24C  
3/085

See application file for complete search history.

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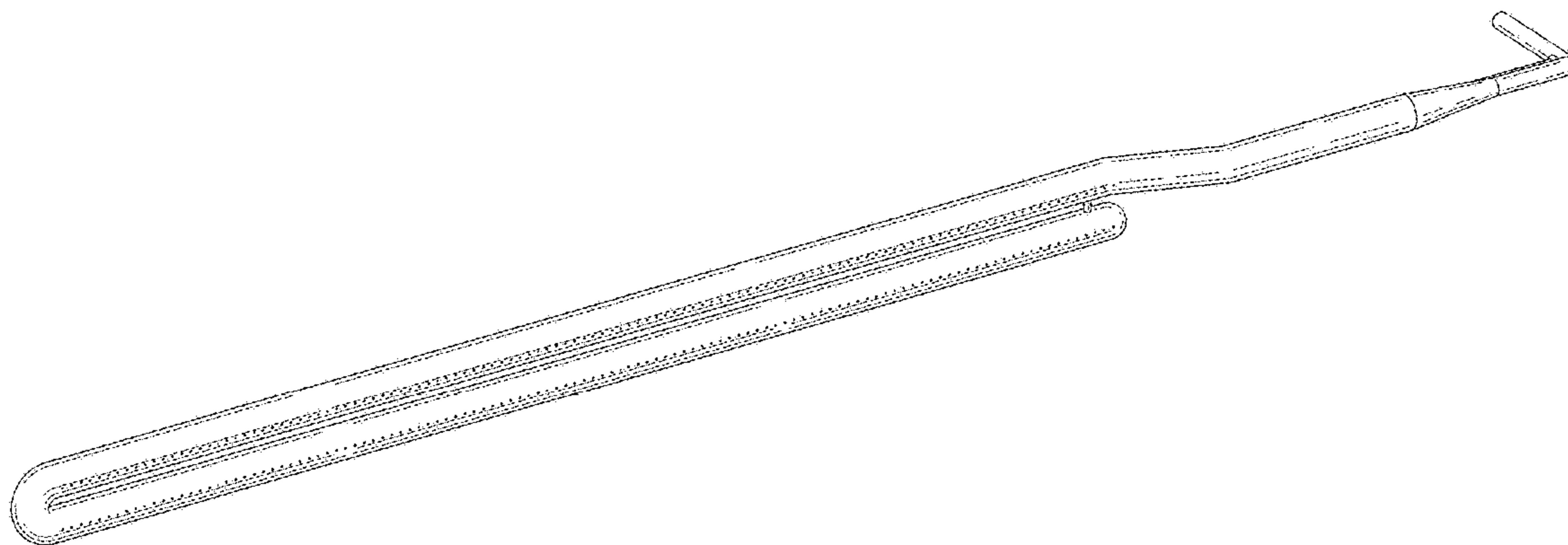
(57) **CLAIM**

We claim the ornamental design for a gas nozzle substrate processing apparatus, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a gas nozzle substrate processing apparatus showing my new design; FIG. 2 is a front elevational view thereof; FIG. 3 is a rear elevational view thereof; FIG. 4 is a top plan view thereof; FIG. 5 is a bottom plan view thereof; FIG. 6 is a left side elevational view thereof; FIG. 7 is a right side elevational view thereof; FIG. 8 is an enlarged right side elevational view thereof; and FIG. 9 is an enlarged portion view taken along line 9-9 in FIG. 2; FIG. 10 is a cross sectional view take along line 10-10 in FIG. 9; and, FIG. 11 is a cross sectional view take along line 11-11 in FIG. 9.

**1 Claim, 5 Drawing Sheets**



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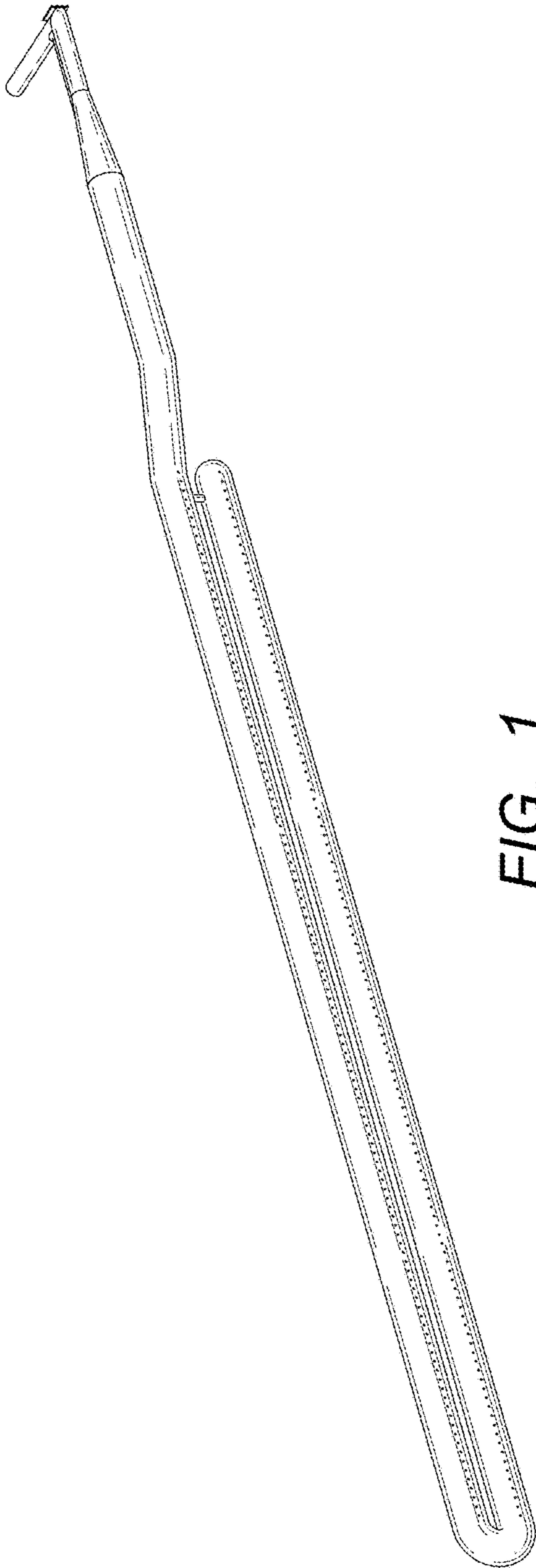


FIG. 1

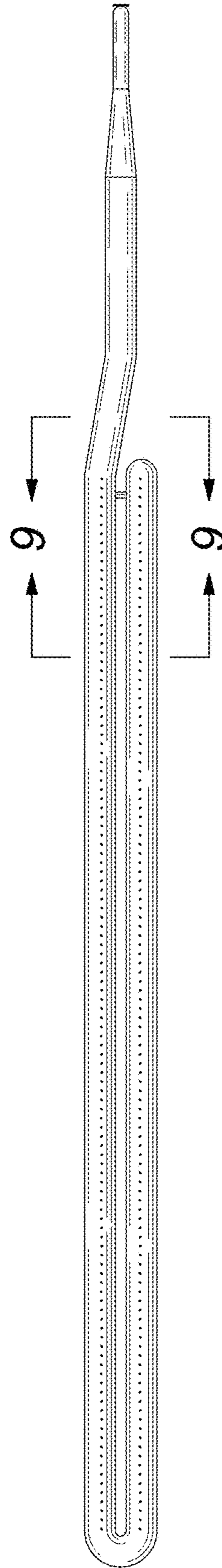


FIG. 2

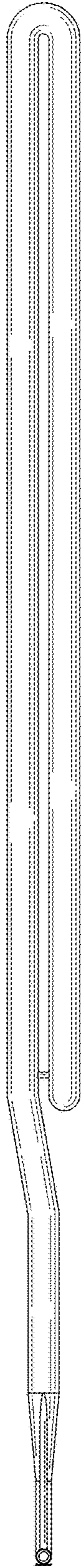


FIG. 3

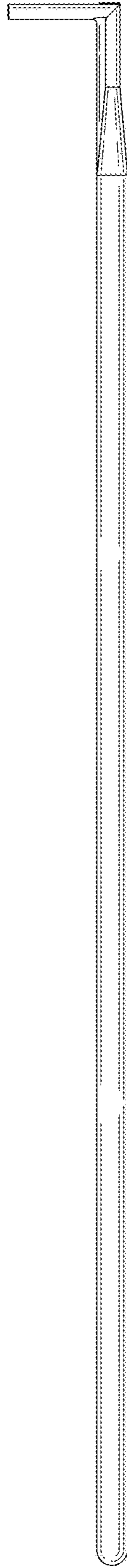


FIG. 4

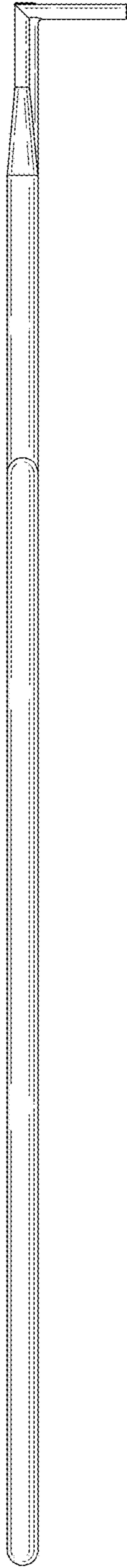


FIG. 5

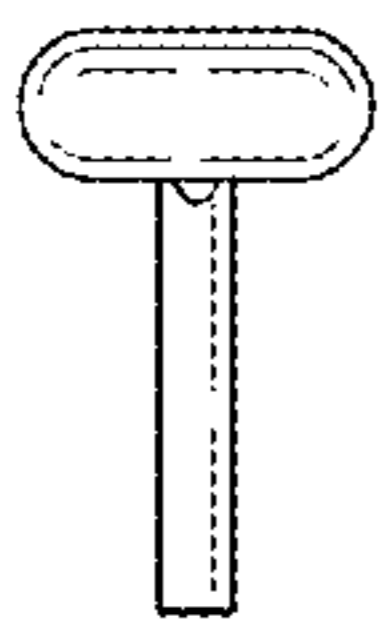


FIG. 6

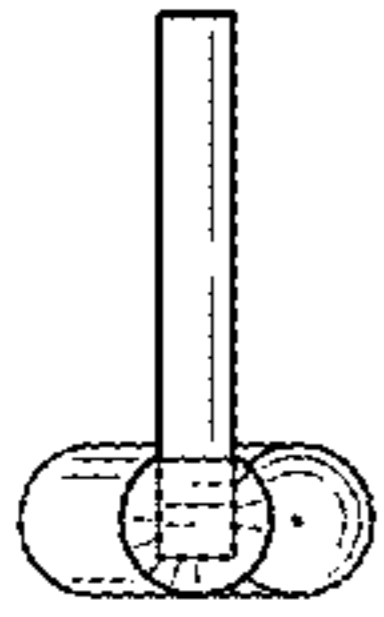


FIG. 7

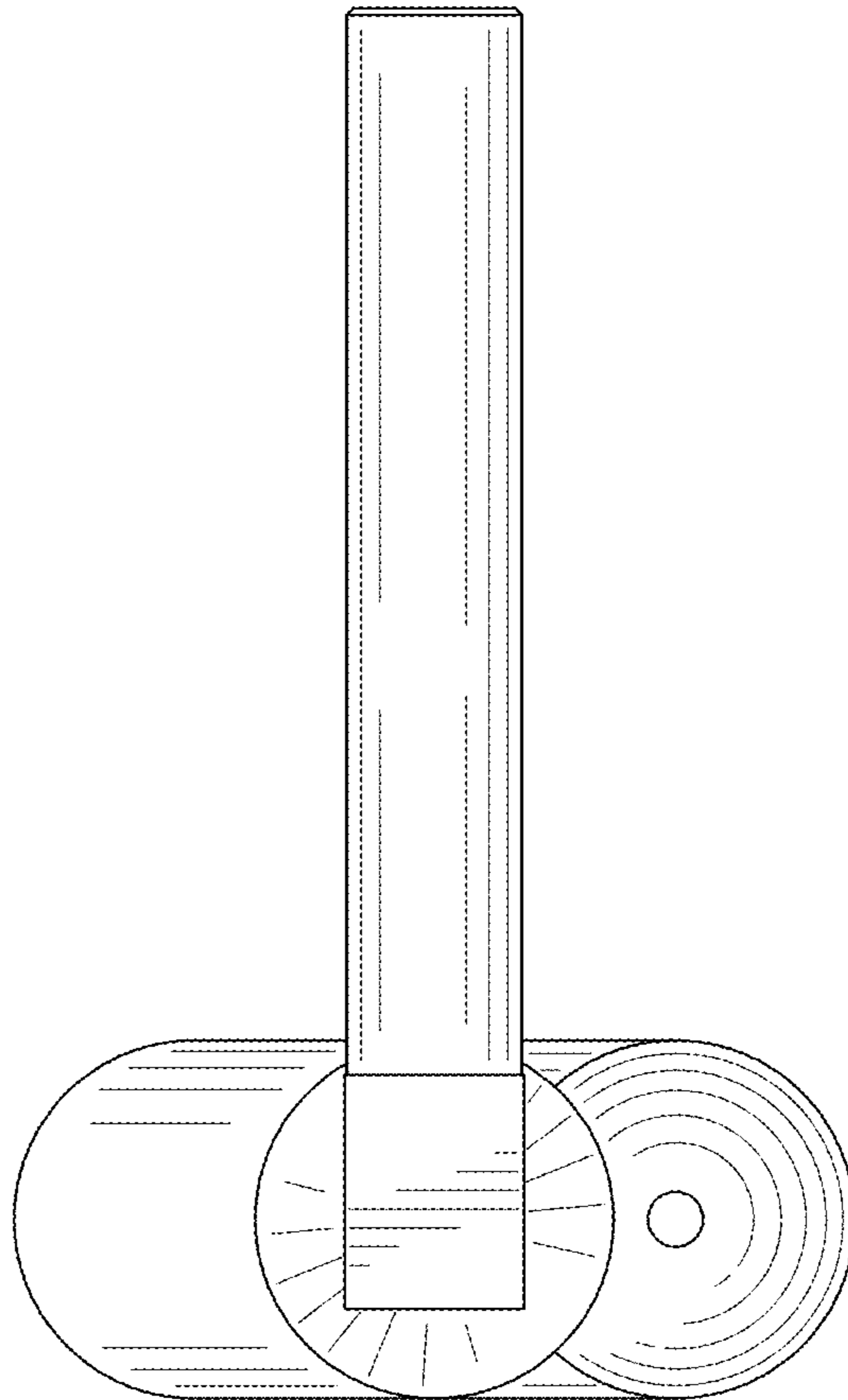


FIG. 8

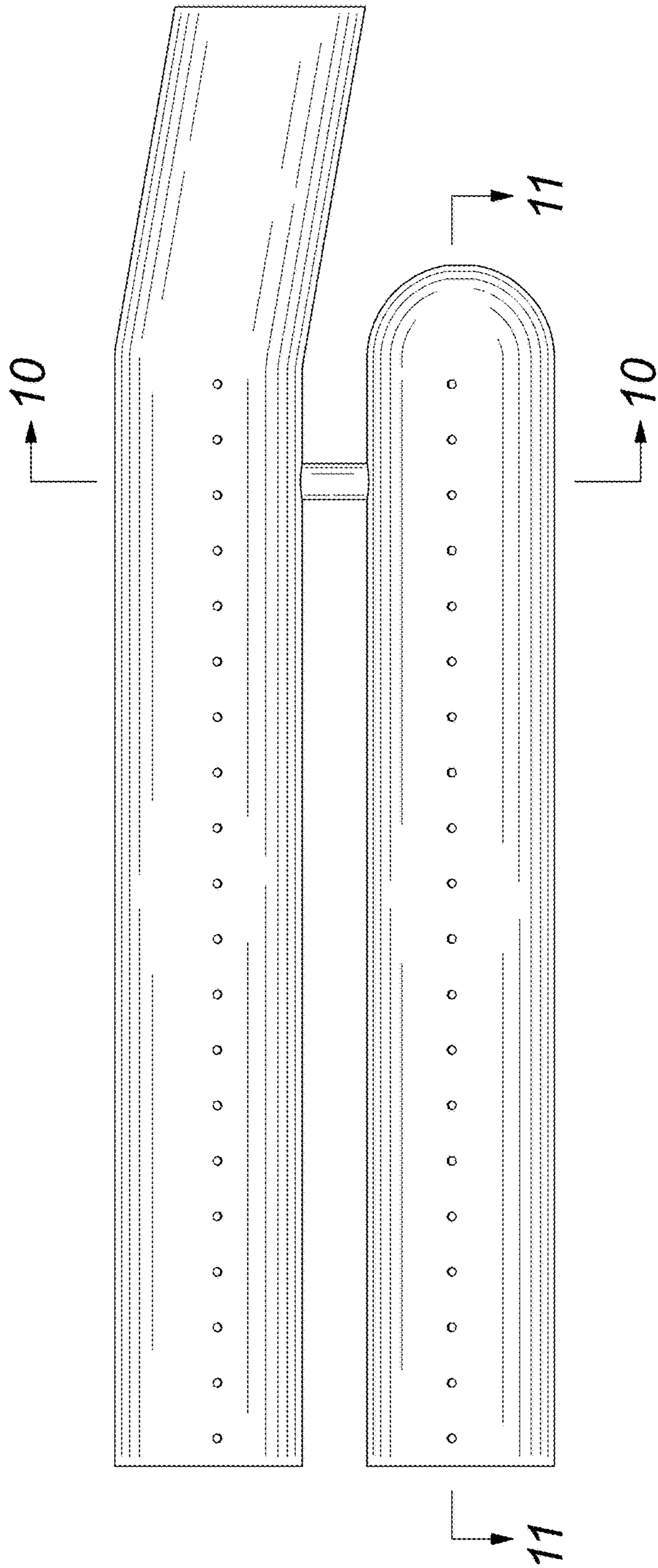


FIG. 9

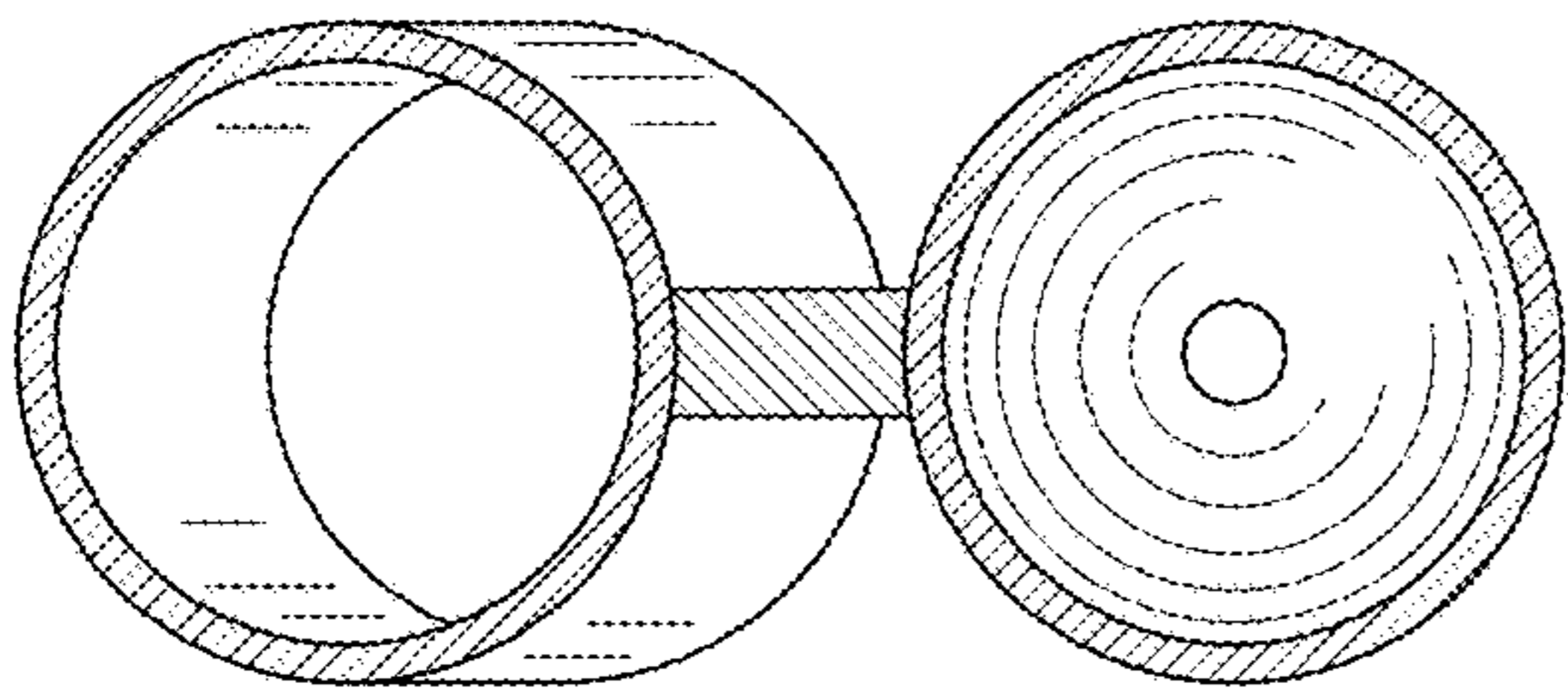


FIG. 10

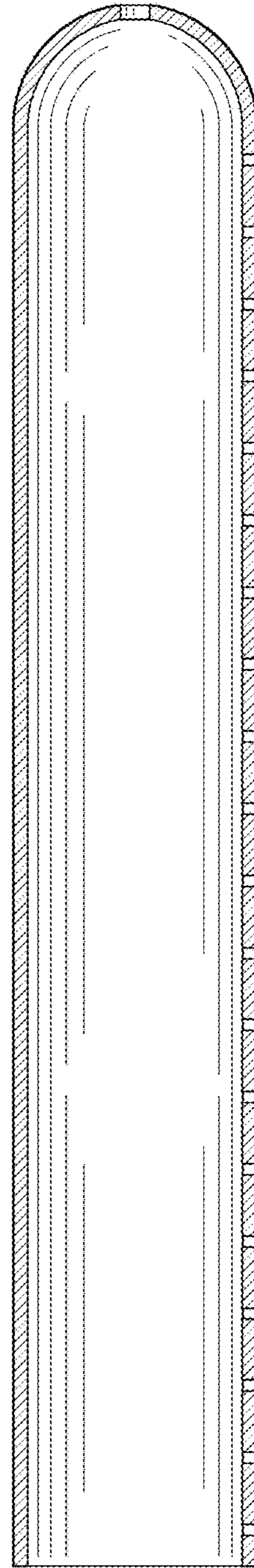


FIG. 11